



Product Change Notification

Change Notification #: 118908-00
Change Title: 2U 12x3.5inch SAS and 2x NVMe Hot Swap Backplane F2U12X35S3PH,
1U 8x2.5 inch SAS/NVMe Hot Swap Backplane F1U8X25S3PHS,
2U Hot-swap 8x2.5inch SAS/NVMe Combo Drive Bay Kit A2U8X25S3PHS,
PCN 118908-00, Product Material, New Alternate Hot Swap Backplane
Date of Publication: February 25, 2022

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material*	March 27, 2022
---	----------------

* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following changes on the items listed in the "Products Affected" table.

- Adding a second source for a Voltage Regulator (VR) controller on the Hot swap backplanes (HSBP). The new controller is identical in function to the previous one but differs in form factor.

The new components have passed all functional and electrical validation tests successfully. As a result, we are adding as alternates the following PBA in the Hot swap backplanes:

A2U8X25S3PHS - H88386-301
F2U12X35S3PH - H88392-401
F1U8X25S3PHS - H88382-401

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers.

Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
2U Hot-swap 8x2.5inch SAS/NVMe Combo Drive Bay Kit	A2U8X25S3PHS	955858	J12659-008	H88386-252 H88386-253 H88386-311	J12659-009	H88386-252 H88386-253 H88386-311 H88386-301
1U 8x2.5 inch SAS/NVMe Hot Swap Backplane	F1U8X25S3PHS	955868	J11107-008	H88382-351 H88382-352 H88382-411	J11107-009	H88382-351 H88382-352 H88382-411 H88382-401
2U 12x3.5inch SAS and 2x NVMe Hot Swap Backplane	F2U12X35S3PH	955869	J10383-006	H88392-351 H88392-411	J10383-007	H88392-351 H88392-411 H88392-401

PCN Revision History:

Date of Revision:

February 25, 2022

Revision Number:

00

Reason:

Originally Published PCN



Product Change Notification

118908-00

INFORMATION IN THIS DOCUMENT IS PROVIDED IN CONNECTION WITH INTEL PRODUCTS. NO LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE, TO ANY INTELLECTUAL PROPERTY RIGHTS IS GRANTED BY THIS DOCUMENT. EXCEPT AS PROVIDED IN INTEL'S TERMS AND CONDITIONS OF SALE FOR SUCH PRODUCTS, INTEL ASSUMES NO LIABILITY WHATSOEVER AND INTEL DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY, RELATING TO SALE AND/OR USE OF INTEL PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

A "Mission Critical Application" is any application in which failure of the Intel Product could result, directly or indirectly, in personal injury or death. SHOULD YOU PURCHASE OR USE INTEL'S PRODUCTS FOR ANY SUCH MISSION CRITICAL APPLICATION, YOU SHALL INDEMNIFY AND HOLD INTEL AND ITS SUBSIDIARIES, SUBCONTRACTORS AND AFFILIATES, AND THE DIRECTORS, OFFICERS, AND EMPLOYEES OF EACH, HARMLESS AGAINST ALL CLAIMS COSTS, DAMAGES, AND EXPENSES AND REASONABLE ATTORNEYS' FEES ARISING OUT OF, DIRECTLY OR INDIRECTLY, ANY CLAIM OF PRODUCT LIABILITY, PERSONAL INJURY, OR DEATH ARISING IN ANY WAY OUT OF SUCH MISSION CRITICAL APPLICATION, WHETHER OR NOT INTEL OR ITS SUBCONTRACTOR WAS NEGLIGENT IN THE DESIGN, MANUFACTURE, OR WARNING OF THE INTEL PRODUCT OR ANY OF ITS PARTS.

Intel may make changes to specifications and product descriptions at any time, without notice. Designers must not rely on the absence or characteristics of any features or instructions marked "reserved" or "undefined". Intel reserves these for future definition and shall have no responsibility whatsoever for conflicts or incompatibilities arising from future changes to them. The information here is subject to change without notice. Do not finalize a design with this information.

The products described in this document may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jcb.ijkk@intel.com

Copyright © Intel Corporation 2022. Other names and brands may be claimed as the property of others.

3D XPoint, Axxia, Basis, Basis Peak, BlueMoon, BunnyPeople, Celeron, Centrino, Cilk, Curie, Flexpipe, Intel, the Intel logo, Intel Atom, Intel CoFluent, Intel Core, Intel. Experience What's Inside, the Intel. Experience What's Inside logo, Intel Inside, the Intel Inside logo, Intel Insider, Intel Joule, Intel RealSense, Intel SingleDriver, Intel SpeedStep, Intel Unite, Intel vPro, Intel Xeon Phi, Intel XScale, InTru, the InTru logo, the InTru Inside logo, InTru soundmark, Iris, Itanium, MCS, MMX, Optane, Ostro, Pali, Pentium, picoArray, Picochip, picoXcell, Puma, Quark, SMARTi, Soletta, Sound Mark, StarPro, Stay With It, the Engineering Stay With It logo, StreamSight, Tarari, The Journey Inside, Thunderbolt, the Thunderbolt logo, Transcede, True Key, Ultrabook, VTune, Xeon, X-GOLD, XMM, X-PMU and XPOSYS are trademarks of Intel Corporation or its subsidiaries in the U.S. and/or other countries.

Microsoft, Windows, and the Windows logo are trademarks, or registered trademarks of Microsoft Corporation in the United States and/or other countries. Java is a registered trademark of Oracle and/or its affiliates. Bluetooth is a trademark owned by its proprietor and used by Intel Corporation under license. Intel Corporation uses the Palm OS* Ready mark under license from Palm, Inc. OpenCL and the OpenCL logo are trademarks of Apple Inc. used by permission by Khronos.

Learn how to use Intel Trademarks and Brands correctly at <http://www.intel.com/intel/legal/tmusage2.htm>.